Form PTQ-1595 (Rev. 03-11) OMB No. 0851-0027 (axp. 03/31/2015)	U.S. DEPARTMENT OF COMMERCE United States Patent and Trademark Office
PATENTS ONLY	
1. Name of conveying party(les):	2. Name and address of receiving party(les)
Yoshimidhi Kumagai (01/25/2010) and Hiroaki Ishiwata (01/25/2010)	Name: Sony Corporation
Additional name(s) of conveying party(les) attached? Yes X No	Internal Address: Street Address;
3. Nature of conveyance/Execution Date(s):	1-7-1 Konan, Minato-ku
Execution Date(s): In parentheses after Inventor name	Tokyo 108-0075
X Assignment Merger Change of Name	JAPAN
Security Agreement Joint Research Agreement	City:
Government Interest Assignment	State:
Executive Order 9424, Confirmatory License	Country:Zip:
Other	Additional name(s) & address(es) Yes X No attached?
A. Patent Application No.(s) 13/974,390 Additional numbers attached?	B. Patent No.(6)
Name and address to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved:
Name: Davy E. Zoneraich LERNER, DAVID, LITTENBERG, KRUMHOLZ & MENTLIK, LLP Internal Address: Atty. Dkt.: SONYJP 3.0-2204 DIV Street Address: 600 South Avenue West	7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00
	Enclosed None required (government interest not affecting title)
City: Westfield	8. Payment information
State: NJ Zip: 07090	
Phone Number: 908-654-5000	
Fax Number: 908-654-7866	Deposit Account Number 12-1095
Email Address: mcormier@ldlkm.com	Authorized User Name Davy E. Zoneraich
9. Signature:	August 26, 2013 Date
Davy E. Zoneraich - 37,267 Name of Person Signing	Total number of pages including cover sheet, attachments, and documents: 2
3267547 J.DOXIA	

PATENT REEL: 031250 FRAME: 0622

Attorney Docket No. SONYJP3.0-2204 SONY Ref. No.: S10P0533US00

ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

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SOLID-STATE IMAGING DEVICE, MANÚFACTURING METHOD OF SOLID-STATE IMAGING DEVICE AND ELECTRONIC APPARATUS

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, SONY CORPORATION, a Japanese corporation, with offices at 1-7-1 Konan, Minato-kn, Tokyo, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint Inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its processors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accuraing or to accurate to me with respect to the filling of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignce of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or roissues of any Letters patent which may be granted for my afterestid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invertion and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

the spaces that follow: Serial Number.	, Filing Date:
This assignment executed on the dates indicated below.	
YOSHIMICHI KUMAGAI	
Name of first or sple inventor KANAGAWA JAPAN	Execution date of U.S. Patent Application
Residence of First or sole inventor. O.Sh. m/ch. Cathon of a l Signature of first or sole inventor	January 25, 20/0 Date of this assignment
HIROAKI ISHIWATA Name of second inventor	Execution date of U.S. Patent Application
TOKYO JAPAN	
Residence of second inventor Hiraaki Ishiwata	January 25, 2010 Date of this assignment
Signature of second inventor	Date of this assignment
Name of third inventor.	Execution date of U.S. Patent Application
Residence of third inventor	
Signature of third inventor	Date of this assignment

PATENT